

Optimizing your test and measurement solution by leveraging the industry's most integrated SoC



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1. Introduction

New challenges are brought to the test and measurement (T&M) market with the ever-increasing availability of new technology and with new ways to connect and interact between man and machine as well as machine to machine. New future-proof and cost efficient T&M products are required to enable effective test and validation not only during product development and product manufacturing, but also throughout the lifetime of the product.

The T&M market can be divided into three sub-segments, each having specific characteristics. The first segment consists of the general-purpose T&M segment, which includes end applications such as oscilloscopes and signal or logic analyzers/generators. This type of equipment is used in many diverse industry branches from lab to manufacturing test to field test. Another segment is the mechanical test segment, which includes non-destructive testing (NDT), industrial X-ray, material testing and highly accurate measurements of physical dimensions like LIDAR. Finally, the third segment consists of telecommunication testing with products for the wireline, wireless, optical and telecommunication markets.

Requirements of these sub-segments can be met by leveraging the processing capacity and acceleration capability of TI's two new system-on-chips (SoCs) **66AK2L06** and **TCI6630K2L** for a cost-effective implementation of T&M products. Both SoCs offer a rich hardware environment as well as a complete software development environment that integrates the functions necessary to generate, process and analyze the signals at all stages, from discrete analog-to-digital converters (ADCs) and digital-to-analog converters (DACs) to the graphical user interface (GUI) connection and external mass storage. The SoCs provide a highly integrated solution with an integrated digital front end (DFE) and a JESD204B interface, enabling seamless connection to high-speed data converters like ADCs, DACs and analog front ends (AFEs). This paper will detail the capabilities and advantages of the 66AK2L06 SoC in the area of general-purpose testers. The paper describes the benefits of the 66AK2L06 SoC for two classes of application: arbitrary signal generators and real-time spectrum analyzers (SAs). The TCI6630K2L SoC is also a cost-effective solution for telecommunication testing products.

2. Application overview

Signal generators are key tools for the T&M market. They produce well-defined signals that enable engineers to explore and test their devices. Early equipment generated simple continuous waveforms, but as the industry of signal processing

has evolved at a fast pace, test signals have become more complex and the control demands on signal generators have increased accordingly. Not only should a modern signal generator have the capability to generate the expected modulated waveform, it should also emulate the impairments and interference that would impact the signal

under test in the field. Such signal generators are now widely used across the industry. The most demanding industries in that respect are wireless communication, aeronautic, satellite and defense applications. They require vector signal generators (VSGs), which produce digitally modulated signals according to predefined formats. Depending on the type of measurements, generated signals may carry information for the purpose of testing user equipment.

The most common vector measurements are power measurements like adjacent channel power ratio (ACPR), sensitivity and selectivity and amplitude/phase errors like error vector magnitude. Accuracy of the measurement depends on the accuracy of the VSG. For example:

1. Power level accuracy affects the measurement of an equipment sensitivity
2. Amplitude-/phase-level accuracy affects the measurement of an equipment signal distortion
3. Frequency level accuracy affects the measurement of an equipment selectivity

Some test applications require that the VSG creates a very clean signal. This can be difficult as the signal generator may introduce errors in the signal. Nevertheless, it is possible to compensate for these impairments using pre-distortion techniques proven in the field of radio communications.

The natural companions of signal generators for the T&M market are SAs. SAs of today range from cheaper swept-tuned SAs that provide a snap shot of the signal in the frequency domain, to vector SAs that add phase information to enable analysis of digital modulation, to real-time SAs that also provide the time domain into the spectrum analysis.

Examples of advanced measurement challenges that modern SAs need to address include:

- Transient and dynamic signal capture and analysis

- Spread spectrum and frequency hopping signals
- Burst transmissions, glitches and switching transients
- Frequency drifting
- Noise analysis
- Modulation analysis including modulation quality diagnostics

When the equipment to be tested is already deployed in the field it is necessary to use portable test equipment. The recent increase in transceiver equipment has facilitated an increase in maintenance and test needs in order to ensure optimal performance of a radio network. It is not possible to use high-precision laboratory equipment such as that used for compliance testing or production testing for on-site testing. Flexible, portable and less expensive test equipment is needed for in-field testing. Furthermore, T&M functionality may be embedded into the equipment for self-calibration or auto-diagnosis purposes.

Portable, embedded test equipment must balance flexibility and precision

requirements with reduced C-SWaP (cost, size, weight and power), which is also referred to as SWaP-C (size, weight, power and cost) in some regions. Such equipment can be built around a monolithic multicore device able to digitally generate or analyze complex signals, to apply or compensate for impairments while drawing its power supply

from a USB or PoE+ outlet. The 66AK2L06 SoC and its rich set of libraries address this challenge.

TI's KeyStone™ SoC-based multicore devices are at the heart of C-SWaP efficiency, with their

Of particular note is the 66AK2L06 SoC, which delivers a flexible and high-performance development platform to address advanced measurement and precision requirements with reduced C-SWaP.

66AK2L06 key features:

- Two ARM Cortex-A15 RISC cores @ 1.2 GHz with 8400 DMIPS
- Four TMS320C66x DSP cores @ 1.2 GHz with fixed- and floating-point processing providing 76 GFLOPS and 153 GMACS
- Integrated DFE technology with programmable filtering, IQ imbalance correction, up and down sampling, etc. offloads heavy signal processing
- Advanced integrated network coprocessor offloads IP routing and IP termination from ARM and DSP cores
- Two Fast Fourier Transform coprocessors (FFTC) improve latency for FFT/inverse FFT (IFFT) execution up to 8K-points with better performance than the fixed-point DSP core implementation
- Multicore Shared Memory Controller (MSMC) with 2MBytes of memory shared by the cores and the accelerators
- Multicore Navigator offers operation of single-core simplicity to multicore SoC software design
- Ethernet switch with 4x 1GbE ports
- Two single-lane PCIe Gen2 interfaces supporting up to 5 GBaud
- High-speed JESD204B chip-to-chip interface supporting up to four lanes each at 7.37 Gbps
- Compact package size: 25 mm × 25 mm FPBGA

cost-effective performance and low power consumption. The new TI 66AK2L06 SoC delivers breakthrough performance and SWaP-C efficiency to the designers of T&M equipment. Based on TI's new **KeyStone II** multicore architecture, the 66AK2L06 SoC integrates a mix of processing elements including TI fixed- and floating-point TMS320C66x digital signal processors (DSPs), ARM[®] Cortex[®]-A15 cores and advanced signal processing accelerators. The 66AK2L06 SoC is equipped with a high-speed JESD204B interface for direct connectivity to TI's high-speed ADCs, DACs and AFEs. Integration of a software-programmable DFE for digital conversion and digital filtering eliminates the need for what would otherwise be a set of discrete components, further reducing power and board space and yielding the best power-per-watt in a small footprint.

3. Description of device

The use of multiple DSP cores is a key technology which facilitates increasingly sophisticated signal-processing algorithms to advance the vanguard of

waveform-intensive applications, such as avionics, radar, sonar, T&M and radio communications. Multicore capabilities combined with an expanding array of AccelerationPacs and an integrated transport solution enable high performance at exceptionally low power consumption in a compact form factor. Depending on the application supported and the interfaces used, the power consumption of the 66AK2L06 SoC ranges from 6W to 12W at 100°C (case temperature).

The key objective behind the KeyStone II platform is to provide connectivity, abundant throughput and on-chip resources so that the processing cores will be able to reach their optimum processing performance without constraints^[3]. Referred to as “multicore entitlement”, the empowerment of processing cores is achieved by the architecture's capability to provide non-blocking access to all processing cores, peripherals, coprocessors and I/O channels. Key aspects of the KeyStone II architecture (see Figure 1 on the following page) are the Multicore Navigator, TeraNet and Multicore Shared Memory Controller, leading to a highly flexible and scalable solution for JESD204B attach applications.

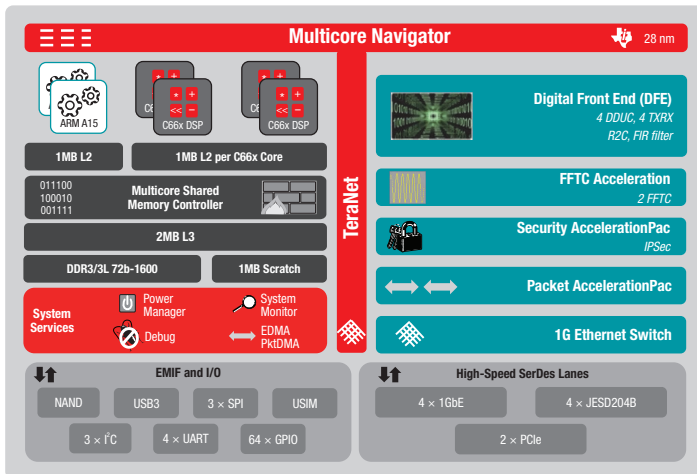


Figure 1: 66AK2L06 SoC block diagram

TI provides a growing number of options to meet the system requirements for **ADCs** and **DACs** with the JESD204B interface that enable a direct connection to the 66AK2L06 SoC. ADCs with JESD204B interface offer sample rates from 50 Msps up to 4 Gsps and resolutions from 12 bit to 16 bit. The devices with higher sampling rate often include configurable and by-passable decimation to enable reduction of the sample rate. DACs with JESD204B interface range from dual-channel devices to quad-channel devices with sample rates from 1.6–2.8 Gsps and a variety of digital features including interpolation, numerically controlled oscillators (NCOs), mixers and gain for optimizing frequency placement and minimizing data input rates. During 2016 TI will build on its foundation of RF-sampling ADCs and DACs with several new families.

4. Arbitrary signal generator

The 66AK2L06 SoC is well suited to implement signal generators as embedded hardware units or as standalone units. It can concurrently produce up to four complex user-defined wave forms

(synthesized using DSPs and Keystone accelerators) or test patterns loaded from external mass storage, with a maximum aggregated bandwidth (BW) of 660 MHz and an achievable occupied bandwidth (OBW) of 350 MHz. The produced signal may be repetitive or single-shot, using an external or internal trigger. The device can also generate modulated test vectors (QAM, QPSK, FSK, BPSK and OFDM) to be used for testing commercial and military radio communication equipment.

Figure 2 on the following page is an example of implementation of a signal generator using the 66AK2L06 SoC (as an arbitrary waveform generator) combined with an analog up-converter.

The 66AK2L06 SoC will perform the following operations:

- **Waveform synthesis:** Based on stored test vectors in external or internal memory or known patterns, the DSPs can create on-the-fly series of baseband complex signals.
- **Streaming:** Baseband complex samples are retrieved from internal memory and presented to the programmable filters at the baseband rate. The streaming can be continuous or started and stopped by triggers. For low-frequency signals it is necessary to perform an interpolation in software before streaming the digital waveforms.
- **Gain adjustment:** The samples amplitude is adjusted so as to maximize the use of the DFE data path.
- **Filtering:** The DFE includes four programmable FIR filter banks, Farrow resampling filters and cascaded-integrator-comb (CIC) filters.
- **Mixing:** NCOs adjust the carrier frequency of the baseband waveform with an accuracy of

$$\frac{DFE_{clock}}{2^{18}}$$

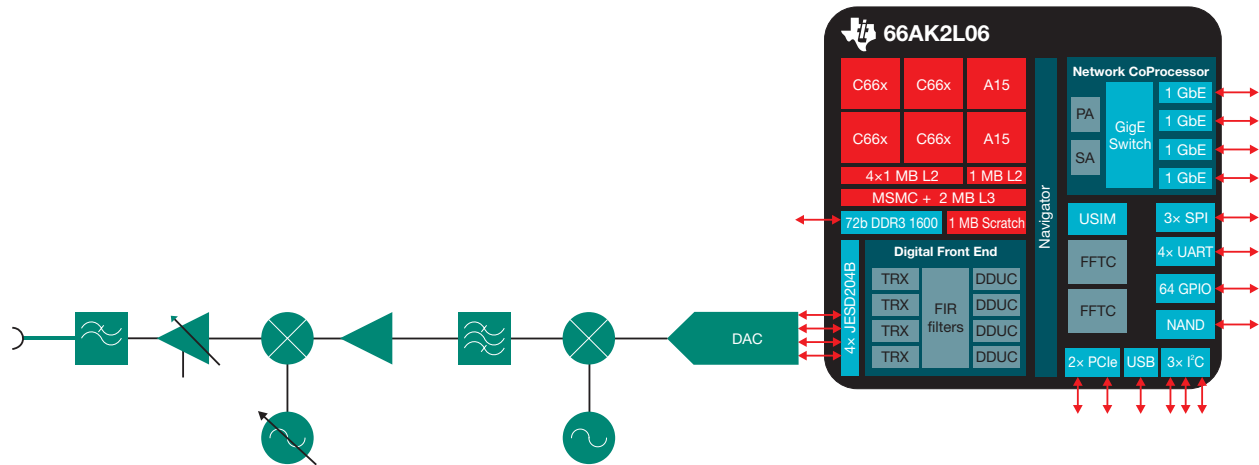


Figure 2: Arbitrary signal generator diagram

- **Combining:** Depending on the BW of the different waveforms, the DFE can combine up to 12 together in the same output stream. The DFE can create four composite streams.
- **Optional analog impairment correction:** Such as IQ distortion correction.

The digital/analog up-converter chain contains a cluster of DACs which may also include interpolation filter, some analog mixers, filters and amplifiers. A large variety of DACs and AFEs from Texas Instruments support JESD204B subclasses

0 and 1. They can connect to the 66AK2L06 SoC, supporting wide spectrum-span or narrow spectrum-span signal generation. Table 1 displays some examples of synthesis configurations that the 66AK2L06 SoC can support. It is worth noting that the device storage capability in size and throughput allows for the generation of long multichannel waveform patterns. The performance of the 66AK2L06 SoC DDR interface enables real-time use of the patterns, even for the highest signal BW.

	DUC in DFE				DUC in DFE/DSP*
Composite analog signal bandwidth	737.28 MHz	368.64 MHz	184.32 MHz	92.16 MHz	92.16 MHz
Maximum number of composite analog channels	1	1	2	4	4
Composite signal sample rate	737.28 Msps	368.64 Msps	184.32 Msps	92.16 Msps	92.16 Msps
Number of digital channels per composite analog signal	1–12	1–12	1–12	1–12	1
Interpolation	1–192	1–192	1–192	1–192	1024
Effective bandwidth of a digital channel	3.07 MHz – 589.82 MHz	1.54 MHz – 294.91 MHz	1.54 MHz – 147.46 MHz	1.54 MHz – 73.73 MHz	0.29 MHz
Sample resolution	2x 16 bits	2x 16 bits	2x 16 bits	2x 16 bits	2x 16 bits
Total pattern length in DDR memory (sec)	0.46 s–87.38 s	0.91 s–174.76 s	1.82 s–174.76 s	3.64 s–174.76 s	932.07 s
Total pattern length in DDR memory (Msamples)	256				

* An 8x interpolation filter is executed on a DSP core, then the DFE-DUC performs a 128x interpolation.

Table 1: Signal generator use case examples

Waveform synthesis

Arbitrary waveforms or test vectors can easily be generated on 66AK2L06 and TCI6630K2L SoCs using the optimized signal-processing libraries for both SoCs and the radio communication accelerators for the TCI6630K2L SoC. DSPLib provides optimized correlation, convolution, filtering and vector operations for 16b and 32b signals. For example, applying a FIR filter on a complex vector (1×1024) takes around 1.13 cycles per tap per sample (i.e., 15.4 microsec for a 16-tap filter on a single 1.2-GHz DSP core). If multiple waveforms are combined in the same composite signal, the same band sampling rate shall be used to form the digital channels associated to the waveforms.

Streaming

Packets of baseband samples associated with multiple digital channels are retrieved by the DFE baseband interface from internal memory (MSMC) or external memory (DDR) and streamed to the filter banks. The 66AK2L06 SoC can stream up to 32 digital channels simultaneously.

Gain, mixing and combining

Depending on the configuration, each DUC filter block can process up to 12 digital channels simultaneously. The DDUC block in the DFE supports:

- Gain, phase and delay adjustment of the digital channels (pre- or post-filtering).
- Interpolation of the digital channels. Interpolation is used to adapt the sampling rate to the frequency span required by the application. Programmable filtering is used to meet the spectral emission requirements of the synthesized signals.
- Up conversion of digital channels. The NCO frequency is either static or varies under the

control of the DSP through the Radio Frequency Software Developer Kit (RFSDK). The latter option enables the synthesis of swept signals (within a 660-MHz span).

Power meters can be used to monitor the power of each of the digital channels separately. Up converted digital channels are optionally aggregated in the same composite signal. The DFE can create four separate composite signals. The frequency span of the composite signals is limited by their allocated BW on the JESD204B interface as described in the examples in Table 1 on the previous page.

Impairment correction

Analog components suffer from impairments such as IQ imbalance and non-linear distortion. For instance, an analog quadrature modulator cannot have identical amplitude on its three branches, nor can its 90° phase shifter be perfect across the total band of the signal. This may have an adverse effect on the quality of the measurements in a test environment, as measurement equipment generally assumes that the transmitter equipment is free from impairments. While some of the impairments may be corrected in the measurement equipment an alternative strategy would be to correct them in the generator.

The 66AK2L06 SoC includes back-end automatic gain control that helps optimize the use of the data converter's range and programmable FIR filters (PFIR) that can be used to optimize either the in-channel performance (thus reducing EVM) or out-of-band performance (thus reducing ACPR). RFSDK software provides a selection of predefined filters with an optimized EVM/ACPR trade-off for LTE and W-CDMA performance. It also allows the user to define its own filter.

More advanced corrections may be implemented by using the capability of the 66AK2L06 or TCI6630K2L SoCs to process simultaneously signal synthesis (“TX path”) and signal measurements (“feedback path”). The synthesized signal can be pre-compensated for the impairment based on a real-time adaptation (blind or calibrated) algorithm executed on a DSP core. The TCI6630K2L SoC enables the necessary feedback path.

Power estimation on the 66AK2L06 SoC

The 66AK2L06 SoC provides multiple ways of monitoring the power of synthesized or received signals. The DFE includes 16 flexible power meters that can be configured to measure the power of streaming signals at different stages of the processing. For signal synthesizers, the DFE can monitor the power of the digital channel components (up to 18 bits range) before and after gain/filtering/interpolating. It can also monitor the power of the digital composite signal after optional combination of the digital channels before and after filtering. For SAs, the DFE can monitor the power of the received signals (up to 24 bits range) and the power of sub-channels after gain/filtering/decimation. The power meters may be used in single-shot mode acting on a trigger or in continuous mode with configurable RMS/Averaging schemes, as well as min/max recording. A software API in RFSDK sets up the power meters and another API reads the power meter values. Control of the measurement sequence in continuous mode is automated through timers and counters. Watermarks may be used on power meters to trigger further processing. For example, advanced spectrum analysis may be triggered on reception of a transient signal. DSPLib also provides a set of C66x optimized functions operating on real or

complex signals in support of more advanced power analysis.

5. Arbitrary spectrum analyzer

The 66AK2L06 SoC is well suited for implementing spectrum analyzer functions. It provides a compact and low-power implementation due to its JESD204B interface that enables a serialized direct connection to the ADC and contains enough processing, filtering and FFT resources to implement the three most common types of spectrum analyzers: the swept tunable SA, the vector SA and the real-time analyzer.

The swept tunable SA is the traditional SA architecture that has been in use for decades. Originally implemented with purely analog components, swept tunable SAs now also contain an ADC and some digital signal processing. It is designed to make frequency vs. power measurements over a wide signal BW by down converting the signal and sweeping it through the passband of a resolution BW filter. The benefit of a swept tunable SA is the large signal BW it can handle in combination with its high dynamic range. The fact that it is sweeping through the BW means it can only calculate the power level at one frequency point at a time and therefore works best in a relatively stable input signal environment.

The vector SA does not only measure the power level but also adds the phase information in order to enable modulation measurements of digitally modulated signals. The VSA digitizes the IF-signal and performs the down conversion, filtering and detection in the digital domain. Transformation from time to frequency domain is done using FFT processing.

The real-time SA performs frequency vs. power and phase measurements. It can display the time domain data and provides seamless signal capture. This enables real-time triggering and time-correlated multi-dimensional measurements that enable detection of dis-continuous signal problems such as glitches, transients, burst transmissions and other dynamic or intermittent phenomena.

This section will focus on how the 66AK2L06 SoC can handle the requirements of a real-time SA since it is the most demanding of the three applications from a digital processing standpoint and is able to emulate the functions of the other two types.

Figure 3 below is a generic block diagram of a real-time SA using the 66AK2L06 SoC.

The AFE of the RTSA can be tuned across the full frequency range of the instrument and down converts the input signal to a fixed IF signal matching the BW of the real time SA. The IF-signal is filtered and digitized before being sent to the SoC over the JESD204B interface. The signal is further down converted and processed in time and frequency domains within the SoC before results are presented.

Signal processing

The 66AK2L06 SoC can support digital signal processing techniques used in spectrum analysis, applied to samples, frames or blocks of data.

- Sample level processing:
 - DDUC accelerators in DFE support filtering of the captured samples. Variable band low-pass filtering can be used to reject part of the incoming signal or to shape it.
 - DDUC blocks in DFE support down conversion of the captured samples and support decimation of the captured samples (I/Q pairs). Decimation is used to adapt the sampling rate to the frequency span required by the user.
- Frame level processing
 - FFTC accelerators support FFT, iFFT, DFT and iDFT.
 - DSPLib provides a large variety of optimized fixed- and floating-point FFTs and DFT C66x routines for real or complex data.

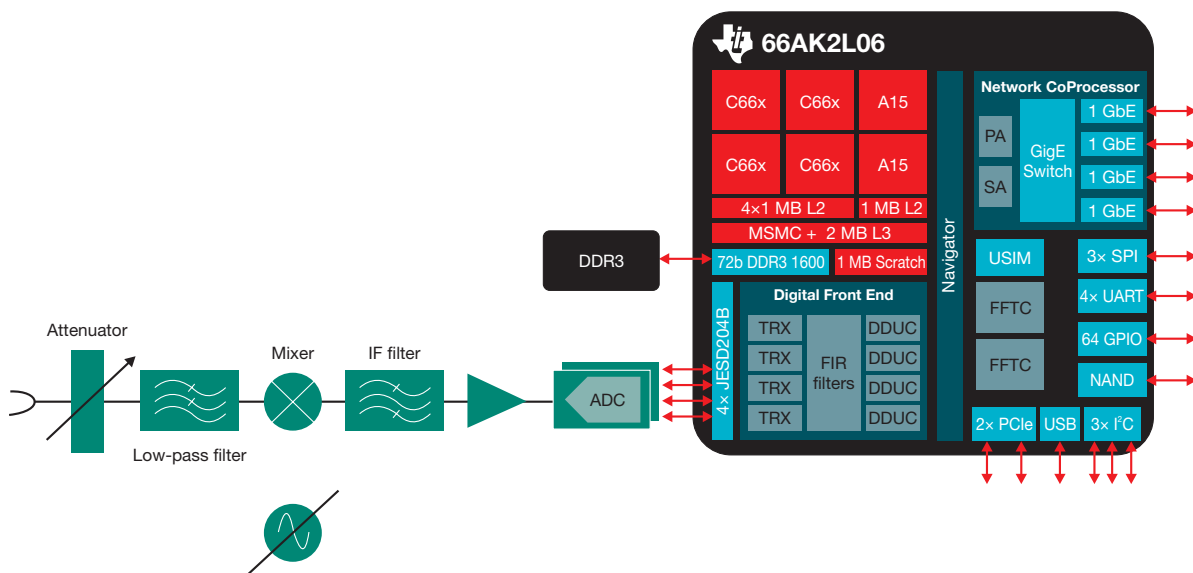


Figure 3: Generic block diagram of a real-time spectrum analyzer

- Block level processing
 - DSPLib provides optimized vector multiplication routines to implement smoothing spectrogram windows.
 - The Multi-Core Software Developer Kit (MCSDK) supports the manipulation of large blocks of data in overlapping spectrograms.
 - DSPLib provides a large variety of filtering, correlation and convolution routines to be used in multi-domain analysis.

Table 2 below presents the performance to expect from the 66AK2L06 SoC depending on the implementation of the Fast Fourier Transform (16b fixed-point I/Q on FFTC, 16b fixed-point I/Q on C66x, floating point (FP) on C66x).

Leveraging the DDC and the filtering in the DFE block in conjunction with the FFT performance of the FFTC and the C66x cores, the 66AK2L06 SoC can support a wide range of SA use cases. The digital down converter in the DFE block has a maximum down conversion ratio of 192. If a higher ratio is required, the DFE limitation can be overcome by leveraging the device DMA infrastructure, as long as the DFE DDC filter is set to meet Nyquist limit for the total decimation. Instead of passing all samples from the DFE to the FFTC, the DMA engine

passes one out of two, four or eight samples. This will increase the maximum decimation to 1,536. If further decimation is needed it can easily be implemented using one of the C66x DSP cores and the appropriate optimized functions from DSPLib. Table 3 on the following page includes a few examples of SA use cases. The example on the far right is using the DSP for down conversion.

The indicated sample rate assumes complex data so 368 Msps corresponds to 736 Msps for real data. This is currently the upper limit of what the 66AK2L06 SoC DFE block is able to support and requires a speed of 7.3 Gbps over two lanes on the JESD204B interface. Future enhancements include running the DFE at higher clock speeds and thus higher sampling rates.

All of the examples in Table 3 on the following page may use continuous acquisition storing the data in DDR memory configured as a FIFO. The highest rate accounts for no more than 12 percent of the DDR BW capacity. This enables real-time triggers to be implemented in the DSP. Once triggered, the data acquisition can either be stopped immediately or can continue to run for a configurable amount of time to store enough data to enable analysis both before and after the trigger point.

		FFT size	16	32	64	128	256	512	1024	2048	4096	8192			
SNR (dB)	16b I/Q on FFTC		91.1	89.3	88.4	86.2	87.5	85.5	85.2	84.8	84.1	83.8			
	16b I/Q on C66x		72.2	69.1	69	67.1	67	65.7	65.6	64.6	64.5	63.7			
	FP on C66x		~300 dB												
FFTs/s	16b I/Q on one FFTC		22.86M	12.97M	9.80M	4.95M	2.98M	1.33M	705k	303k	154k	66k			
	16b I/Q on one C66x											175k	75k	36k	9k
	FP on one C66x											74k	35k	9k	4k
GFLOPS	16b I/Q on FFTC		7.3	10.4	18.8	22.2	30.5	30.6	36.1	34.1	37.8	35.4			
	16b I/Q on C66x											9.0	8.4	8.9	5

FFT performance measured in GFLOPS uses the following complex transform formula where T is the time (in ns) to execute one FFT and N is the FFT size

$$GFLOPS = \frac{5N \log_2 N}{T}$$

Table 2: FFT performance table

	DDC in DFE					DDC in DSP
	Super side span	Wide span	Medium span	Medium span	Narrow span	Narrow span
Spectrum bandwidth	330 MHz	20 MHz	1 MHz	1 MHz	1 kHz	1 kHz
Sample rate	368 Msps	368 Msps	368 Msps	368 Msps	368 Msps	368 Msps
Decimation	1	12	128	128	1536*	131072
Effective sample rate	368 Msps	31 Msps	3 Msps	3 Msps	240 ksps	3 ksps
Time domain resolution (sample)	2.72 ns	32.61 ns	347.83 ns	347.83 ns	4.17 μ s	356.17 μ s
FFT size	8196	8196	8196	1024	8196	2048
Spectrogram time resolution (frame length)	22 μ s	267 μ s	2851 μ s	356 μ s	34 ms	729 ms
Sample size	32 bits	32 bits	32 bits	32 bits	32 bits	32 bits
Maximum record length with MSMC (2 MB memory)	178 μ s	2137 μ s	23 ms	23 ns	274 ms	23342 ms
Maximum record length with DDR (8 GB memory)	729 ms	8.75 s	93 s	93 s	1120 s	26.6 h
Frequency resolution (FFT bin width)	44.9 kHz	3.7 kHz	0.35 kHz	2.8 kHz	29.2 Hz	1.4 Hz

* Decimation achieved by a combination of DDC and DMA.

Table 3: Spectrum analyzer example use cases for a single channel

In order to avoid spectrum leakage caused by discontinuities between the FFT frames, a combination of windowing and overlapping FFT frames can be applied. The windowing deemphasizes the samples close to the edge of the FFT frame where the artificial spurious responses would occur while the overlapping FFT frames will ensure that spectral events close to the frame edge are not lost due to the windowing. The windowing can be implemented by post-processing the results of the FFTC, using DSP cores and optimized library functions. The two FFTC accelerators are able to fully offload all of the FFT processing including the use of overlapping FFT frames, reserving the use of the DSP resources for advanced signal processing tasks. The Packet DMA engine solves the intense internal data management by moving data between memory-mapped locations without any processor intervention. A descriptor, associated to every block of data, identifies the source and destination address for the move, as well as the data structure.

The descriptors are generated by the processing cores or by the peripherals. They are distributed in hardware queues managed by the Multicore Navigator.

Another function that could be offloaded to the DFE block is the IQ-imbalance correction that would be implemented using logic within the JESD204B receiver block. Correction parameters are estimated either based on complex gain imbalance correction information from the JESD204B block or based on a single-tap blind estimation algorithm. This function would be useful when a zero IF complex stream is input to the RX sub-block.

Triggers

The 66AK2L06 SoC enables flexible triggers of different types to be implemented. The triggers can be used to either start or stop data acquisition. These can be split into two main categories.

1. External triggers can trigger through a transition on one of the 64 GPIOs or through messaging

passed through one of the complex I/Os including PCIe, Ethernet, I²C, SPI, UART, USB or the JESD204B.

2. Internal triggers are generated by the cores or by signal-processing accelerators. One of the most interesting families of internal triggers is generated by the DFE. While processing the data from the ADC, it can generate a trigger based on the characteristics of incoming data. Examples of internal triggers include:

- **Power based DFE triggers:** These can be based on the power level of the digitized signal from the ADC before filtering and decimation looking at the full spectrum or the power level after filtering and decimation. The DFE block has a number of built-in power meters that can provide power measurements before and after DDC and filtering.
- **Software-based frequency triggers:** A frequency-based trigger can be implemented in software using the C66x DSPs and is therefore very flexible. The DSPs are able to post-process all the results from the FFTCs enabling complex frequency masks to trigger on specific power levels being above or below the defined threshold in selected parts of the spectrum. To enable the analysis in real time, the packet DMA engine is used for all internal DMA traffic between the DSP cores and the FFTC, offloading the DSP cores and minimizing stalls.

As the trigger analysis runs in real time, software-defined timers can be used to detail how much data shall be stored in DDR before and after the trigger point to enable the user to do analysis of the spectrum both before and after the trigger occurred.

6. I/O connectivity

In addition to greater integration at the silicon level, the 66AK2L06 SoC enables a small bill of materials (BOM), reducing board production costs through the use of high-performance serial interfaces such as JESD204B, PCIe, 1 GbE, USB and SPI. They simplify circuit board design and layout, and enable a vast number of ways to connect and present the analyzed data. See Figure 4 on the following page.

USB

The USB interface is a general-purpose cable-bus supporting data exchange between a host and several peripherals. It can interface with a PC or a graphics processor such as TI **Sitara™ processors**. The interface can also be used as a hard drive port for mass storage.

The 66AK2L06 SoC has two bidirectional USB lanes. Each lane supports Full/High/Super-speed modes in both directions in both peripheral and host mode. When in host mode, the Low speed mode is also supported. The controller is backward compatible with USB 2.0. All software drivers needed for the USB interface are available through the **MCSDK**.^[2]

1 GbE

The 66AK2L06 SoC has a five-port (four external) gigabit Ethernet switch for 802.3-compliant Ethernet traffic. The four external ports are independent SGMII modules that can be configured individually. The 66AK2L06 SoC can also implement a Linux®-based web server to enable remote control. A web server is available in the RFSDK for the control and operation of the DFE subsystem.

The Network Coprocessor – (NetCP) resides behind the gigabit Ethernet switch and implements

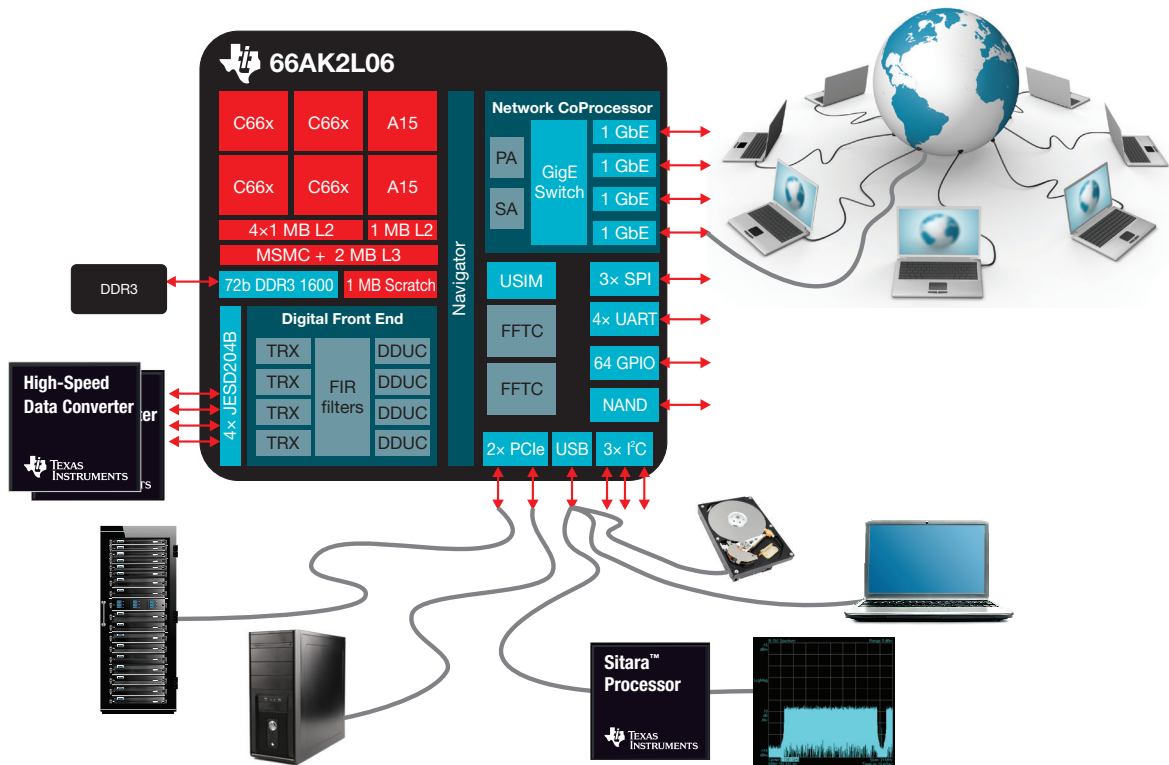


Figure 4: 66AK2L06 I/O connection options

a packet accelerator (PA) for header processing such as header matching and CRC generation, a security accelerator for encryption and decryption operations and a packet DMA controller for internal packet communication.

The NetCP is able to handle up to 1500 kpps. The PA supports ingress features like L3 reassembly, access control list (ACL) processing and multi-route processing, on egress IP-fragmentation, L2 framing and L4 checksum is supported. The security accelerator supports up to 6.4 Gbps of encryption and decryption for IPSEC (IKE, AH, ESP, SRTP), 3GPP and others. Other functions include true random number generation and public key accelerator. All low-level drivers (LLD) needed to drive the NetCP are available in the NetLib software that is part of the **MCSDK**.^[2]

PCIe

The PCIExpress (PCIe) module is a high-speed serial interface that provides a reliable general-purpose connection primarily used over PCB or backplane to connect to other PCIe-compliant devices. Each lane can be operated with a raw bit rate up to 5.0 Gbps. All software drivers needed for the PCIe interface are available through the MCSDK. For more information on the PCIe interface see ^[2].

An extension to the PCIe interface commonly used within automated test systems is PCI Express eXtensions for Instrumentation (PXI Express). PXI and PXI Express are industry standards governed by the PXI Systems Alliance (PXISA) and provide a cheap, robust and high-speed interface based on standard PCI/PCIe interfaces. On top of the PCI/PCIe interface, timing and synchronization features have been added to enable accurate remote control

of the measurement system. The 66AK2L06 SoC supports PCIe and with buffered GPIO signals can also be used to enable a PXIe board design.

SPI

The Serial Peripheral Interconnect (SPI) port is a synchronous serial input/output port that allows a bit stream of programmable length to be shifted in/out [2]. The main intent behind the SPI port is to provide a connection to a SPI ROM for boot. The 66AK2L06 SoC has three SPI ports that can operate at speeds up to 66 MHz. All necessary drivers for the interface are part of the MCSDK.

JESD204B

JESD204B provides a high-throughput, low-pin-count serial link between ADCs, DACs, DSPs, SoCs, field programmable gate arrays (FPGAs) and application-specific integrated circuits (ASIC). The interface enables a low-power implementation with reduced board space and complexity compared to traditional CMOS or LVDS implementations. More information on the benefits of JESD204B can be found in [6].

The JESD204B interface on the 66AK2L06 SoC consists of four bidirectional SERDES lanes operating at rates up to 7.3 Gbps. It connects directly to the DFE block. The DFE uses the lanes

separately or combined to transport one, two or four data streams in each direction. The DFE can split or aggregate up to 12 digital channels on each of the data streams. The interface supports JESD204B subclass 0 for backward compatibility with JESD204A and subclass 1 that supports deterministic latency. See Figure 5.

7. 66AK2L06 SoC development environment

Besides providing powerful hardware resources, the 66AK2L06 SoC comes with a rich set of development tools and libraries, that can kick-start a design, shorten the overall development time and sustain upgrades throughout the life of the product. An evaluation module and reference design is also available.

- **66AK2L06 Evaluation Module** – The 66AK2L06 SoC evaluation module with the JESD204B interfaces rooted to an FMC connector. This module connects seamlessly to TI DACs and ADC evaluation modules.[6]
- **TI Design TIDEP0034** – a reference design connecting TI’s **ADC12J4000** and **DAC38J84** to the 66AK2L06 SoC through the JESD204B interface. For more information see [4].
- **Code Composer Studio™** Integrated Development Environment (IDE) provides an integrated development environment supporting all TI processor platforms and is used to develop and debug embedded applications. It consists of a suite of tools including C/C++ compiler, source code editor, project build environment, debugger, profiler, libraries and many other features.

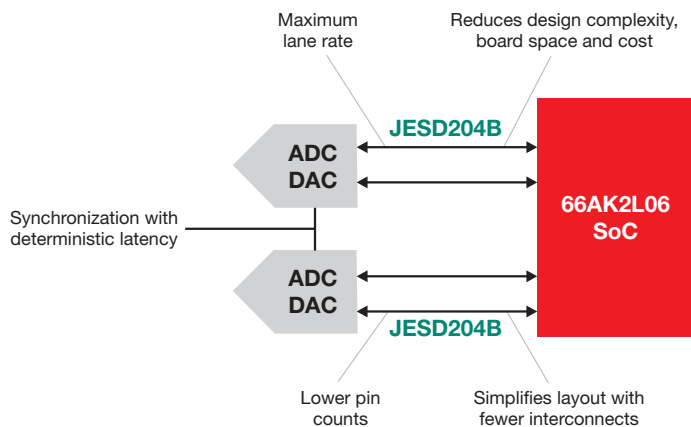


Figure 5: JESD interface benefits

- **MCSDK** – Provides foundational software for TI ARM and DSP-based devices. It includes components like:
 - SYS/BIOS real-time embedded operating system on DSP cores
 - Linux high-level operating system running on ARM processors (SMP mode for multicore ARM processors)
 - DSP chip support libraries, DSP/ARM drivers, and basic platform utilities
 - Inter-processor communication across cores and devices
 - SoC resource management
 - Trace debug and instrumentation
 - Bootloaders and boot utilities, power-on self-test
 - Latest toolchain (Linaro, DSP TI CodeGen)
 - Host tools, integrated development environment
- **DSPLib** – The library, delivered in source as part of Code Composer Studio IDE, contains a large portfolio of digital signal processing functions used as building blocks in various applications. These routines are highly optimized utilizing all the features of the C66x core and include both fixed- and floating-point kernels. DSPLib includes following functions:
 - Adaptive filtering
 - Correlation
 - Fast Fourier Transform
 - Filtering and convolution
 - Matrix computations
- **RFSDK** – Contains a set of APIs that are used to setup and control the DFE block inside the 66AK2L06 SoC, the JESD204B interface and also any ADC, DAC or AFE connected to the JESD interface.

- **NetLib/TransportNetLib**, delivered as a part of the MCSDK, consists of a software package for ARM user space applications to gain access to NetCP. The NetLib includes two main software components, the High-Performance Lib (HPLIB) and Network API (NetAPI) modules. The HPLIB is a low-overhead library optimized for fast path applications (user plane, UDP/IP) while the NetAPI contains send/receive APIs along with data path configurations (control plane, GTP/IP).

8. Conclusion

Based on TI's high-throughput KeyStone II architecture, the 66AK2L06 SoC is a scalable, low-power solution with a superior processing system including integrated FFT hardware acceleration, DFE, high-speed JESD204B interface and a network coprocessor with an integrated GBE switch.

The platform offers FFT performance, using the FFTCs and C66x DSP cores, up to 46 MFFT/s with an SNR that ranges from 84 dB (fixed point) to 300 dB (floating point). The JESD204B interface provides a high-speed, low-power connection directly to the analog front end or data converters.

The C66x cores together with the rich set of provided signal-processing source code libraries bring efficient signal-processing capacity, while the ARM Cortex-A15 cores provide access to a large set of Linux-based and open-source libraries and services. These features together with the rich set of I/Os makes it an excellent SoC platform for the demanding requirements of the T&M market including SWaP-C, time to market and future proof-ness.

This device offers designers of T&M applications a single hardware and software platform to address

a variety of applications for signal generation and signal analysis. It enables differentiated features with product lifetime upgrades as well as field upgrades. Designers can get started today with the 66AK2L06 SoC and TI high-speed data converters on the evaluation module.^[4]

References

[1] Hardik Gandhi, Debbie Greenstreet, Joe Quintal Digital, Texas Instruments white paper “**Radio Front-End strategies provide game-changing benefits for small cell base stations**”.

[2] **66AK2L06 technical documents**

[3] TCI6630K2L SoC, **High-performance, low-power solution for indoor enterprise PoE+ small cells and outdoor pico deployments.**

[4] **66AK2L06 DSP+ARM SoC JESD204B Attach to Wideband ADCs and DACs** TI Reference Design

[5] **Ready to make the jump to JESD204B?**

[6] **66AK2L06 Evaluation Module**

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